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PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-298364

(43)Date of publication of application : 18.11.1997

(51)Int.Cl.

H05K 3/46

H05K 1/11

H05K 3/34

(21)Application number : 09-048210

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(22)Date of filing : 03.03.1997

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(30)Priority

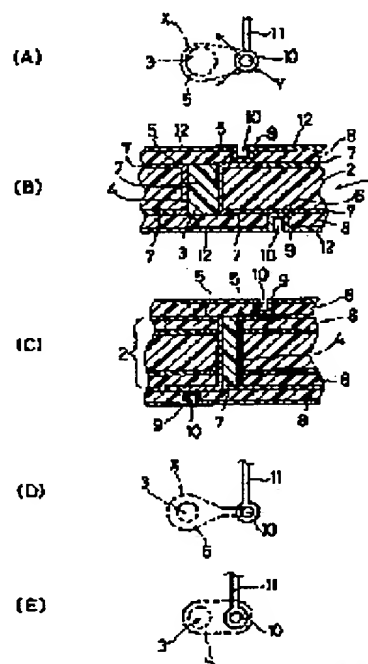
Priority number : 08 75297 Priority date : 04.03.1996 Priority country : JP

(54) MULTILAYER PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To stably connect vias to pads if the pads deviate from a mask film by forming tear-drop-like lands of through-holes to be electrically connected to the vias of a multilayer wiring board.

SOLUTION: The multilayer printed wiring board 1 has a core board 2 having through-holes 3 and a layer insulating layer 8 formed on the upper surface of the board 2. This layer 8 has through-hole lands 5 having recesses where vias 10 are formed below which a conductor layer 9 is formed and circuit pattern 11 connected to this layer 9 is also formed. The through-holes 5 have tear-drop shapes and vias 10 are connected in the through-hole lands 5 which are hence integrated with pads connected to the vias 10. Thus, the connection area is expanded to stabilize the connection.

**LEGAL STATUS**

[Date of request for examination] 03.09.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]